

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	220	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open\$6) and (feed\$6 assembl\$6) and (edge project\$6) and (mov\$6 displac\$6 adjust\$6) and (support receiv\$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 08:59
S1	11	ep-726598-\$ did. jp- 07205214-\$ did. jp- 07183317-\$ did. jp- 07080895-\$ did. jp- 04184944-\$ did. jp- 57128930-\$ did. wo- 2001017012-\$ did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/04 11:34
S2	1	wo-0117012-\$ did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/04 11:44
S3	16316	257/787.ccls. 257/ e21.502.ccls. 257/ e21.504.ccls. 257/ e21.705.ccls. 257/ e23.116.ccls. 257/ e23.125.ccls. 438/108. ccls. 438/124.ccls. 438/126.ccls. 438/127.ccls. 156/500.ccls. 425/117.ccls. 425/125.ccls. 425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/08 15:05
S4	348	425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/04/08 15:07

S5	13000	S3 and ((encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment carrier substrate board pwb pcb integrated ic))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 15:55
S6	8176	S3 and ((encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment carrier substrate board pwb pcb integrated ic) same (cavity feed\$6 assembl\$6 edge project\$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:00
S7	1608	S3 and ((encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment carrier substrate board pwb pcb integrated ic) same (cavity feed\$6 assembl\$6) same (edge project\$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:06
S8	876	S3 and ((encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed\$6 assembl\$6) same (edge project\$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:08

S9	351	S3 and ((encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed\$6 assembl\$6) same (edge project\$6) same (movable displac\$6 support receiv\$6 force part))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/04/08 16:13
S10	2809	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity feed\$6 assembl\$6) and (edge project\$6) and (movable displac\$6 support receiv\$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:14
S11	838	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open\$6) and (feed\$6 assembl\$6) and (edge project\$6) and (movable displac\$6 support receiv\$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:16

S12	68	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open\$6) and (feed\$6 assembl\$6) and (edge project\$6) and (movable displac\$6) and (support receiv\$6 force part)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:17
S13	103	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open\$6) same (feed \$6 assembl\$6) same (edge project\$6) same (movable displac \$6) same (support receiv\$6 force part)	US-PGPUB; USPAT	OR	ON	2008/04/08 16:19
S16	364	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open\$6) same (feed \$6 assembl\$6) same (edge project\$6) same (mov\$6 displac \$6 adjust\$6) same (support receiv\$6 force part)	US-PGPUB; USPAT	OR	ON	2008/04/08 23:20

4/9/08 10:59 AM

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